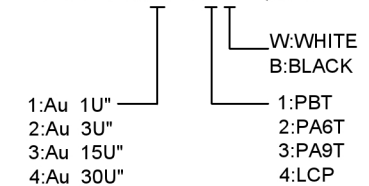


RECOMMENDED PCB LAYOUT(T=0.80±0.05)
COMPONENT SIDE(GENERAL TOLERANCE:±0.05)

NOTE:
1.MATERIAL SPECIFICATION:
1.HOUSING:LCP,UL94 V-0.
2.TERMINAL: COPPER ALLOY
3.MID PLATE: STAINLESS STEEL
4.FRONT SHELL: STAINLESS STEEL
5.EMI PLATE: STAINLESS STEEL
2.PLATING SPECIFICATION:
2-1.TERMINAL:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
2-2.FRONT SHELL:
PLATING SPECIFICATIONS FOLLOW THE P/N
2-3.MID PLATE&EMI PLATE:
CLEAR ONLY
3.MECHANICAL PERFORMANCE:
3-1.INSERTION FORCE: 0.5-2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf-2.0kgf.
3-3.DURABILITY: 10000 CYCLES.
4.ELECTRICAL PERFORMANCE:
4-1. VOLTAGE RATING:100V DC/AC (RMS. max)
CURRENT RATING:3.0A MAX
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE.AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -30°C~+85°C.
6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

U263-24XN-4BQC15



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Δx					ANGULAR	±5°
Δx					L ≤ 4	±0.2
Δx					4 < L ≤ 16	±0.3
MARK	DESCRIPTION	DATE	REVISED	APPROVED	16 < L ≤ 63	±0.4
					L > 63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	
www.helloxkb.com www.helloxkb.cn www.xk-dg.cn						



DSND		SCALE: N/A	MODEL TYPE:	Type-C 3.1
DWN		VIEW:	PART NO.:	
CHKD		UNIT: mm/in	DWG NO.:	U263-24XN-4BQC15
APPD		SIZE: A4	WEIGHT	SHEET
XKB INDUSTRIAL PRECISION CO., LIMITED			1/1	REVISION
				A0